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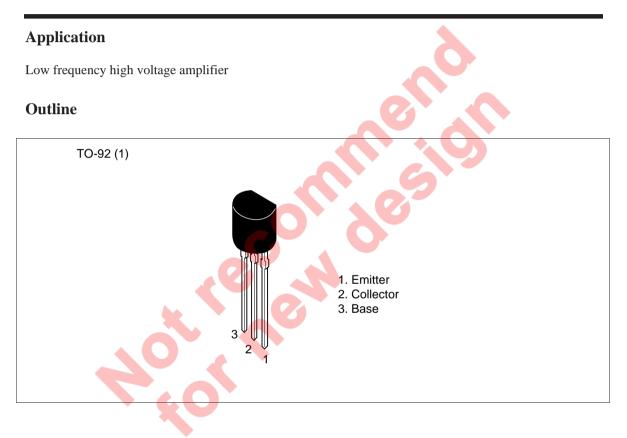
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Silicon NPN Epitaxial

RENESAS

ADE-208-1163 (Z) 1st. Edition Mar. 2001



Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

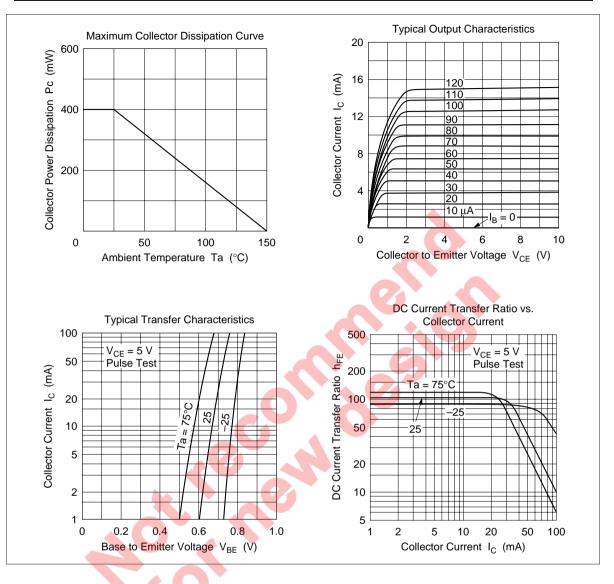
Item	Symbol	2SD2030	2SD2031	Unit
Collector to base voltage	V _{CBO}	160	200	V
Collector to emitter voltage	V _{CEO}	160	200	V
Emitter to base voltage	V _{EBO}	5	5	V
Collector current	Ι _c	100	100	mA
Collector power dissipation	Pc	400	400	mW
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	_55 to +150	°C

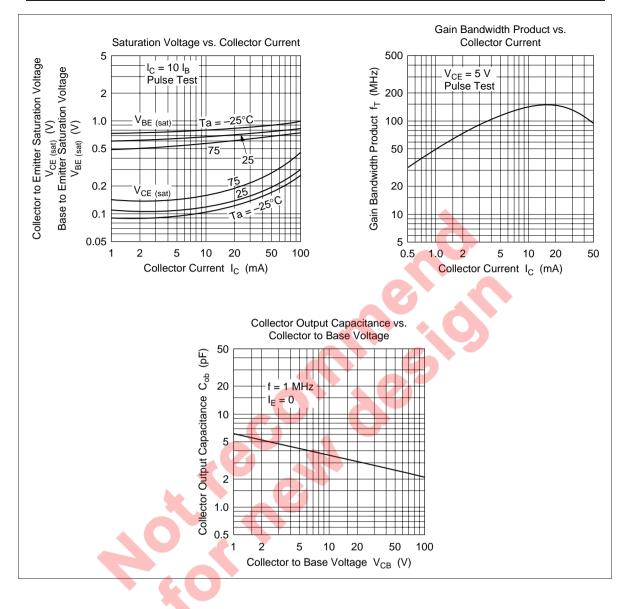
Electrical Characteristics (Ta = 25°C)

	-		- 3				
							6
Electrical Characteristics (Ta = 25°C)							
Item		Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	2SD2030	V _{(BR)CBO}	160	_	5	V	$I_{c} = 10 \ \mu A, I_{E} = 0$
	2SD2031		200				
Collector to emitter breakdown voltage	2SD2030	$V_{\rm (BR)CEO}$	160		-	V	$I_c = 1 \text{ mA}, R_{BE} = \infty$
	2SD2031	_	200				
Emitter to base brea voltage	kdown	V _{(BR)EBO}	5	-		V	$I_{\rm E} = 10 \ \mu A, \ I_{\rm C} = 0$
Collector cutoff current	2SD2030	I _{CBO}	-	-	10	μΑ	$V_{CB} = 140 \text{ V}, I_{E} = 0$
	2SD2031	_					$V_{CB} = 160 \text{ V}, I_{E} = 0$
DC current transfer ratio		h _{FE1} *1	60	_	200		$V_{ce} = 5 \text{ V}, \text{ I}_{c} = 10 \text{ mA}$
		h _{FE2}	30	_	_		$V_{ce} = 5 \text{ V}, \text{ I}_{c} = 1 \text{ mA}$
Base to emitter volta	age	V _{BE}	_	_	1.5	V	$V_{ce} = 5 \text{ V}, \text{ I}_{c} = 10 \text{ mA}$
Collector to emitter s voltage	saturation	V _{CE(sat)}		—	0.5	V	$I_{c} = 30 \text{ mA}, I_{B} = 3 \text{ mA}$
Gain bandwidth proc	duct	f _T		140	_	MHz	$V_{ce} = 5 \text{ V}, \text{ I}_{c} = 10 \text{ mA}$
Collector output capacitance C _{ob}		C _{ob}		3.8	—	pF	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$
Note: 1. The 2SD2030 and 2SD2031 are grouped by h_{FE1} as follows.							
Grade B	С						
	100 10		•				

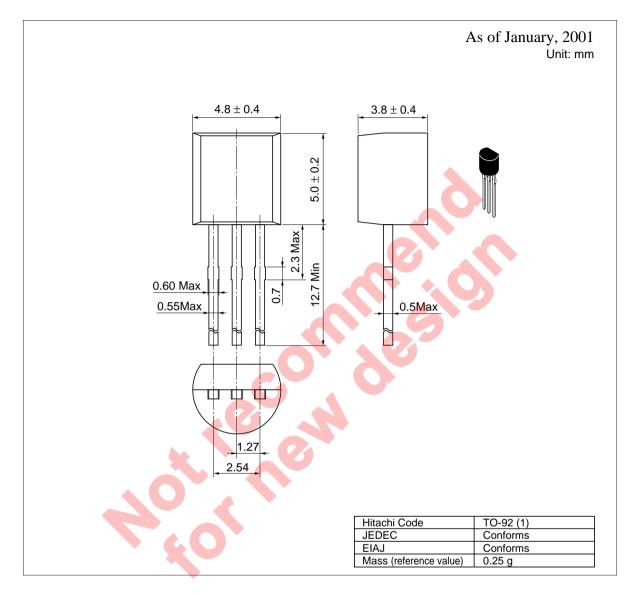
100 to 200 $\boldsymbol{h}_{\text{FE1}}$ 60 to 120







Package Dimensions



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